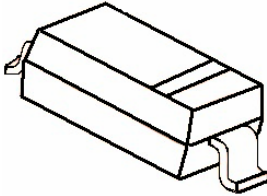


SOD-123 贴片塑封肖特基二极管
SOD-123


Marking: 1N5817W: SJ
1N5818W: SK
1N5819W: SL

SOD-123 Plastic-Encapsulate Schottky Barrier Diode
特征 Features

- 大电流承受能力。High Current Capability
- 正向压降低。Low Forward Voltage Drop

机械数据 Mechanical Data

- 封装: SOD-123 封装 SOD-123 Small Outline Plastic Package
- 极性: 色环端为负极 Polarity: Color band denotes cathode end
- 环氧树脂 UL 易燃等级 Epoxy UL: 94V-0
- 安装位置: 任意 Mounting Position: Any

极限值和温度特性(TA = 25°C 除非另有规定)

Maximum Ratings & Thermal Characteristics (Ratings at 25°C ambient temperature unless otherwise specified.)

参数 Parameters	符号 Symbol	1N5817W	1N5818W	1N5819W	单位 Unit
最大可重复峰值反向电压 Maximum repetitive peak reverse voltage	VRRM	20	30	40	V
最大均方根电压 Maximum RMS voltage	VRMS	14	21	28	V
最大直流阻断电压 Maximum DC blocking voltage	VDC	20	30	40	V
最大正向平均整流电流 Maximum average forward rectified current	IFM	1.0			A
峰值正向浪涌电流 8.3ms 单一正弦半波 Peak forward surge current 8.3 ms single half sine-wave	IFSM	9			A
典型热阻 Typical thermal resistance	RθJA	250			°C/W
功率消耗 Power Dissipation	PD	500			mW
存储温度 Storage temperature range	TSTG	-50-+150			°C

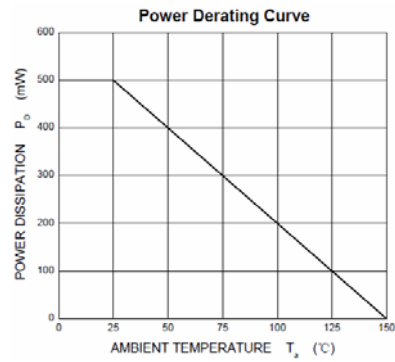
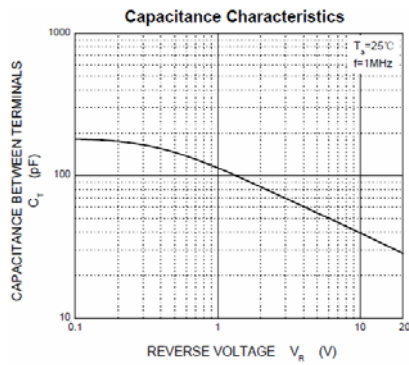
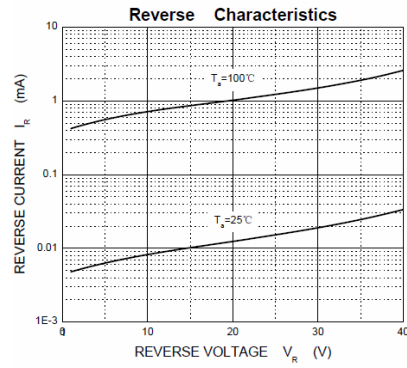
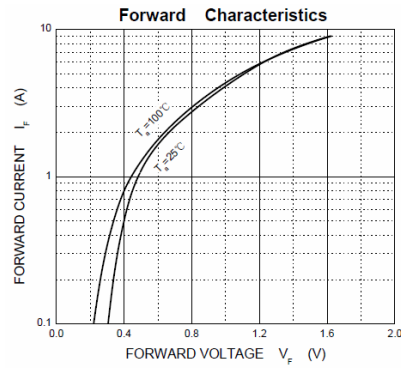
电特性 (TA = 25°C 除非另有规定)

Electrical Characteristics (Ratings at 25°C ambient temperature unless otherwise specified).

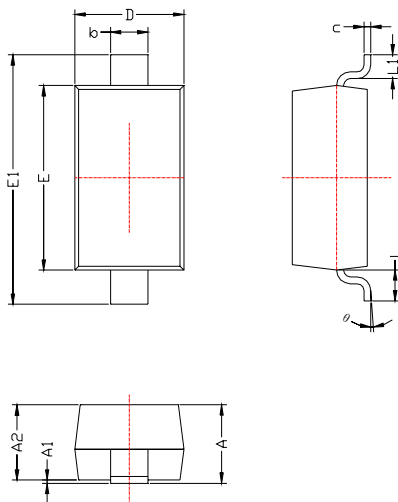
参数 Parameters	符号 Symbol	测试条件 Test conditions	B5817W	B5818W	B5819W	单位 Unit
最大正向电压 Maximum forward voltage	VF	IF = 1.0A IF = 3.0A	0.450 0.750	0.550 0.875	0.600 0.900	V
最大反向电压 Maximum reverse breakdown voltage	VR	IR=1mA	20	30	40	V
最大反向电流 Maximum reverse current	IR	VR=20V B5817W VR=30V B5818W VR=40V B5819W	1.0			mA
典型结电容 Type junction capacitance	Cj	VR = 4.0V, f = 1MHz	120			pF



特性曲线 Characteristic Curves

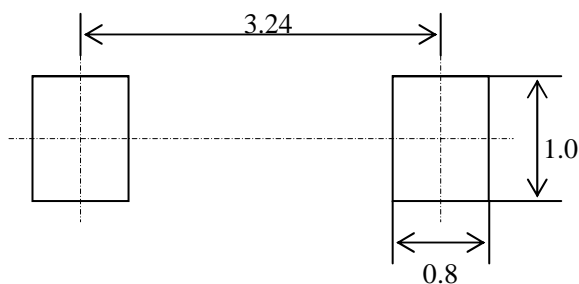


SOD-123 PACKAGE OUTLINE Plastic surface mounted package



SYMBOL	DIMENSION μm	
	MIN.	MAX.
A	1.050	1.250
A1	0.000	0.100
A2	1.050	1.150
b	0.450	0.650
c	0.080	0.150
D	1.500	1.700
E	2.600	2.800
E1	3.550	3.850
L	0.500REF	
L1	0.250	0.450
θ	0 $^\circ$	8 $^\circ$

焊盘设计参考 Precautions: PCB Design (Recommended land dimensions for SOD-123 diode. Electrode patterns for PCBs)



技术要求:
1, 塑封体尺寸: 2.70 X 1.60
2, 未注公差为: ± 0.05
3, 所有单位: mm